

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q80899

Takashi UDAGAWA

Appln. No.: 10/594,683

Group Art Unit: 2826

Confirmation No.: 2074

Examiner: Kevin V. QUINTO

Filed: September 28, 2006

For: COMPOUND SEMICONDUCTOR DEVICE, PRODUCTION METHOD OF
COMPOUND SEMICONDUCTOR DEVICE AND DIODE

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

ATTN: Office of Initial Patent Examination
Filing Receipt Correction
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and
request the following correction:

Assignment For Published Patent Application

SHOWA DENKO K.K., Tokyo, JAPAN

Verification for the requested correction is indicated on the Assignment filed September
28, 2006.

Respectfully submitted,



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WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: June 25, 2009



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
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APPLICATION NUMBER	FILING or 371 (c) DATE	GRP ART UNIT	FIL FEE REC'D	ATTY DOCKET NO	TOT CLAIMS	IND CLAIMS
10/594,683	09/28/2006	2826	900	Q80899	9	3

CONFIRMATION NO. 2074

CORRECTED FILING RECEIPT



CC000000035784577

23373
SUGHRUE MION, PLLC
2100 PENNSYLVANIA AVENUE, N.W.
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WASHINGTON, DC 20037

Date Mailed: 05/01/2009

Receipt is acknowledged of this non-provisional patent application. The application will be taken up for examination in due course. Applicant will be notified as to the results of the examination. Any correspondence concerning the application must include the following identification information: the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please submit a written request for a Filing Receipt Correction. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections.

Applicant(s)

Takashi Udagawa, Chichibu-shi, JAPAN;

*Assignment for Published Patent Application
SHOWA DENKO K.K., Tokyo, JAPAN*Power of Attorney: The patent practitioners associated with Customer Number 23373

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP05/06534 03/28/2005
and claims benefit of 60/560,268 04/08/2004

Foreign Applications

JAPAN 2004-098876 03/30/2004

If Required, Foreign Filing License Granted: 05/22/2007

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US 10/594,683**

Projected Publication Date: Not Applicable

Non-Publication Request: No

Early Publication Request: No

ASSIGNMENT

405047:JS
CSP-20035
For Non-U.S. Clients
US(58) /1

Whereas, I/we Takashi UDAGAWA of c/o SHOWA DENKO K.K., 1505, Shimokagomori,
Chichibu-shi, Saitama-ken, Japan

hereinafter called assignor(s), have invented certain improvements in COMPOUND SEMICONDUCTOR DEVICE,
PRODUCTION METHOD OF COMPOUND SEMICONDUCTOR DEVICE AND DIODE
and executed an application for Letters Patent of the United States of America therefor on

August 21, 2006

; and

Whereas, SHOWA DENKO K.K. of 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo,
Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to
any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named
assignee, its successors and assigns, the entire right, title and interest in the application and the
invention disclosed therein for the United States of America, including the right to claim priority under
35 U.S.C. § 119, and I/we request the Director - U.S. Patent and Trademark Office to issue any
Letters Patent granted upon the invention set forth in the application to the assignee, its successors
and assigns; and I/we will execute without further consideration all papers deemed necessary by the
assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request my/our attorneys SUGHRUE MION, PLLC of 2100
Pennsylvania Avenue, N.W., Washington, D.C. 20037-3213 to insert here in parentheses
(Application number _____, filed _____) the filing date and
application number of said application when known.

Date: August 21, 2006

s/

Takashi Udagawa
Takashi UDAGAWA

Date:

s/

Date:

s/

Date:

s/

Date:

s/